

LPKF Press release

LPKF introduces its new MicroLine C-Series PCB cutting and depaneling system

Delivering cost savings for circuit carrier laser-cutting

Garbsen, April 2005 - LPKF Laser & Electronics AG presents its MicroLine C-series laser system for cutting and depaneling assembled and unassembled printed circuit board panels at high speeds. The MicroLine C delivers contact-free operation, so it easily separates assembled circuit boards without subjecting the boards to production stress. It cuts any aperture shape and produces accurate contours around densely-populated component areas.

With its powerful CO2 laser, the MicroLine C does not require any expensive mechanical tools or adapters to accurately cut circuit boards on its system table. This makes it a cost-effective solution for processing medium-sized and small-quantity jobs. A fiducial recognition system makes the MicroLine C more accurate than mechanical or tool-based processes by using layout reference marks to adapt the working data to the position and size of the circuit.

The MicroLine C is also capable of cutting and drilling various organic materials, as well as structuring organic layers.

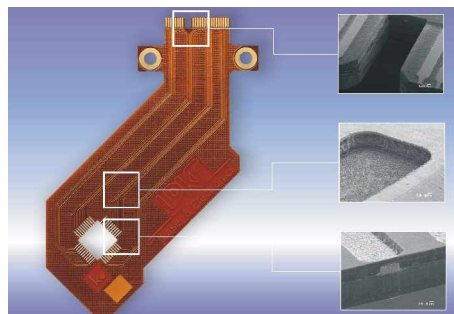
Types: 1153

Picture: circuit board

Detail above: cutting flex circuits

Detail middle: embedded chips

Detail bottom: Opening cover foil



For further information please contact us at:

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